

NPN High-Power Transistors TIP33C

Designed for general-purpose power amplifier and switching applications.

Features

- ESD Ratings: Machine Model, C; > 400 V Human Body Model, 3B; > 8000 V
- Epoxy Meets UL 94 V-0 @ 0.125 in
- These Devices is Pb-Free*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	60	Vdc
Collector - Base Voltage	V _{CBO}	60	Vdc
Emitter – Base Voltage	V _{EBO}	5.0	Vdc
Collector Current - Continuous - Peak (Note 1)	I _C	10 15	Adc Apk
Base Current - Continuous	Ι _Β	3.0	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	80 0.64	Watts W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	−65 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.56	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	35.7	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

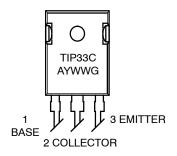
1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.



TO-247 CASE 340L STYLE 3

10 AMPERE NPN SILICON POWER TRANSISTORS 60 & 100 VOLT, 80 WATTS

MARKING DIAGRAM



TIP33C = Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
TIP33CG	TO-247 (Pb-Free)	30 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

TIP33C

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Sustaining Voltage (Note 2) (I _C = 30 mA, I _B = 0)	V _{CEO(sus)}	60	_ _	Vdc
Collector–Emitter Cutoff Current $(V_{CE} = 30 \text{ V}, I_B = 0) \text{ (}V_{CE} = 60 \text{ V}, I_B = 0)$	I _{CEO}	-	0.7	mA
Collector-Emitter Cutoff Current (V _{CE} = Rated V _{CEO} , V _{EB} = 0)	I _{CES}	-	0.4	mA
Emitter-Base Cutoff Current $(V_{EB} = 5.0 \text{ V, } I_{C} = 0)$	I _{EBO}	-	1.0	mA
ON CHARACTERISTICS (Note 2)				
DC Current Gain $(I_C = 1.0 \text{ A}, V_{CE} = 4.0 \text{ V})$ $(I_C = 3.0 \text{ A}, V_{CE} = 4.0 \text{ V})$	h _{FE}	40 20	- 100	_
Collector–Emitter Saturation Voltage ($I_C = 3.0 \text{ A}, I_B = 0.3 \text{ A}$) ($I_C = 10 \text{ A}, I_B = 2.5 \text{ A}$)	V _{CE(sat)}	_ _	1.0 4.0	Vdc
Base-Emitter On Voltage ($I_C = 3.0 \text{ A}, V_{CE} = 4.0 \text{ V}$) ($I_C = 10 \text{ A}, V_{CE} = 4.0 \text{ V}$)	V _{BE(on)}	_ _	1.6 3.0	Vdc
DYNAMIC CHARACTERISTICS				
Small–Signal Current Gain ($I_C = 0.5 \text{ A}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$)	h _{fe}	20	_	-
Current-Gain — Bandwidth Product (I _C = 0.5 A, V _{CE} = 10 V, f = 1.0 MHz)	f _T	3.0	_	MHz

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

TIP33C

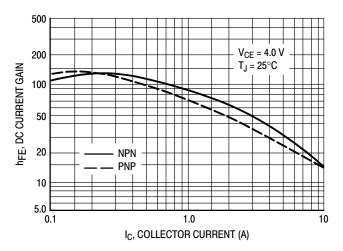


Figure 1. DC Current Gain

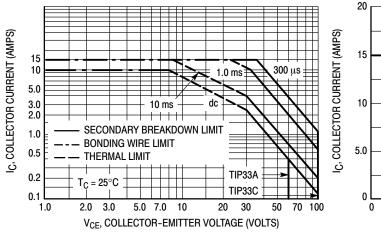


Figure 2. Maximum Rated Forward Bias Safe Operating Area

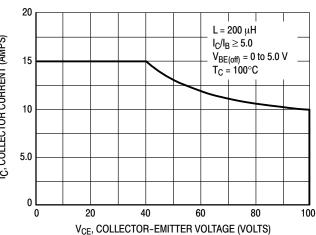


Figure 3. Maximum Rated Forward Bias Safe Operating Area

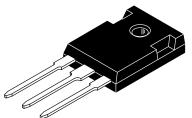
FORWARD BIAS

The Forward Bias Safe Operating Area represents the voltage and current conditions these devices can withstand during forward bias. The data is based on T_C = 25°C; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10%, and must be derated thermally for T_C > 25°C.

REVERSE BIAS

The Reverse Bias Safe Operating Area represents the voltage and current conditions these devices can withstand during reverse biased turn-off. This rating is verified under clamped conditions so the device is never subjected to an avalanche mode.





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DATE 06 OCT 2021

NOTES:

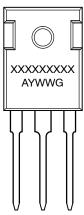
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	INCHES	
DIM	MIN.	MAX.	MIN.	MAX.	
Α	20.32	21.08	0.800	0.830	
В	15.75	16.26	0.620	0.640	
С	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Ε	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45	BSC	0.215 BSC		
Н	1.50	2.49	0.059	0.098	
J	0.40	0.80	0.016	0.031	
К	19.81	20.83	0.780	0.820	
L	5.40	6.20	0.212	0.244	
N	4.32	5.49	0.170	0.216	
Р		4.50		0.177	
Q	3.55	3.65	0.140	0.144	
U	6.15 BSC		0.242	BSC	
W	2.87	3.12	0.113	0.123	

	SCALE 1:1	
2X F	B	SEATING PLANE PLANE T SEATING PLANE H

⊕ 0.25 (0.010)**W** Y AS

GENERIC MARKING DIAGRAM*



STYLE 1:		STYLE 2:	
PIN 1.	GATE	PIN 1.	ANOI
2.	DRAIN	2.	CATH
3.	SOURCE	3.	ANOI
4.	DRAIN	4.	CATH

STYLE 5: PIN 1. CATHODE

2. ANODE

3. GATE 4. ANODE

HODE (S) DDE 2 HODES (S)

PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

STYLE 3: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

XXXXX = Specific Device Code Α = Assembly Location

Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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